

Title (en)
INTEGRATED SYSTEM FOR PROCESSING SEMICONDUCTOR WAFERS

Title (de)
INTEGRIERTES SYSTEM ZUR BEARBEITUNG VON HALBLEITERSCHEIBEN

Title (fr)
SYSTEME INTEGRE DE TRAITEMENT DE PLAQUETTES A SEMI-CONDUCTEURS

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Application
EP 03739583 A 20030217

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Abstract (en)
[origin: WO03068421A2] An integrated process tool for chemical mechanical processing, cleaning and drying a semiconductor workpiece is provided. The integrated process tool includes a CMP module and a cleaning and drying module. After being processed, the workpiece is transported from the CMP module to the cleaning and drying module using a movable housing. In the cleaning and drying module, a cleaning mechanism is used to clean the workpiece while the workpiece is rotated and held by a support structure of the movable housing. A drying mechanism of the cleaning and drying module picks up the workpiece from the moveable housing and spin dries it. Throughout the CMP process, cleaning and drying, the processed surface of the wafer faces down.

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IPC 8 full level
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